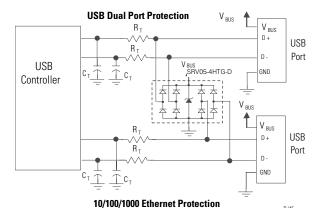
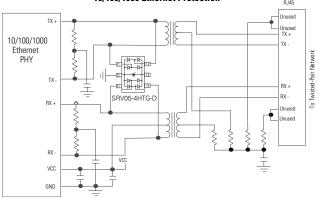


#### **Application Examples**





#### **Description**

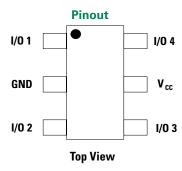
The SRV05-4HTG-D integrates low capacitance rail-to-rail diodes with an additional zener diode to protect each I/O pin against ESD and high surge events. This robust device can safely absorb 10A surge current per IEC 61000-4-5, 2nd Edition (tP=8/20 $\mu$ s) without performance degradation and a minimum  $\pm 30$ kV ESD per IEC 61000-4-2. Their very low loading capacitance also makes them ideal for protecting high speed signal pins.

#### **Features and Benefits**

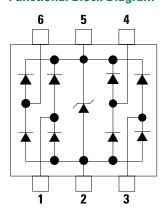
- ESD, IEC 61000-4-2, ±30kV contact, ±30kV air
- EFT, IEC61000-4-4, 40A (5/50ns)
- Lightning, IEC 61000-4-5 2nd Edition, 10A (8/20µs)
- Low capacitance of 1pF (TYP) per I/O
- Low leakage current of 0.5μA (MAX) at 5V
- Small SOT23-6 (JEDEC MO-178) packaging
- Halogen free, lead free and RoHS compliant
- Moisture Sensitivity Level (MSL -1)

#### **Applications**

- LCD/PDPTVs
- Monitors
- Notebooks
- 10/100/1000 Ethernet
- Firewire
- Set Top Boxes
- Flat Panel Displays
- Portable Medical



#### **Functional Block Diagram**



Life Support Note:

#### Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

#### **Absolute Maximum Ratings**

Symbol	Parameter	Value	Units
I <sub>PP</sub>	Peak Current (t <sub>p</sub> =8/20µs)	10	А
$P_{Pk}$	Peak Pulse Power (t <sub>p</sub> =8/20µs)	150	W
T <sub>OP</sub>	Operating Temperature	-40 to 125	°C
T <sub>stor</sub>	Storage Temperature	-55 to 150	°C

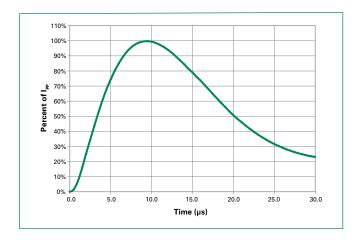
Caution: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### Electrical Characteristics (T<sub>OP</sub>=25°C)

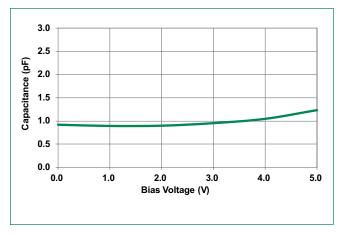
<b>.</b>						
Parameter Symbol		Test Conditions	Min	Тур	Max	Units
Reverse Standoff Voltage	$V_{RWM}$	-			6	V
Breakdown Voltage	$V_{\mathtt{BR}}$	$I_R = 1 \text{mA}$ , I/O to GND	6	8.5		V
Reverse Leakage Current	I <sub>LEAK</sub>	$V_R$ =5V, I/O to GND		0.1	0.5	μΑ
Clamp Voltage <sup>1</sup>	V <sub>c</sub>	$I_{pp}$ =5A, $t_p$ =8/20 $\mu$ s, I/O to GND		11.7	13	V
		$I_{pp}$ =8A, $t_{p}$ =8/20 $\mu$ s, I/O to GND		12.5	14	V
		$I_{pp}$ =10A, $t_p$ =8/20 $\mu$ s, I/O to GND		13.2	15	V
Dynamic Resistance <sup>2</sup>	R <sub>DYN</sub>	TLP, $t_p = 100$ ns, I/O to GND		0.28		Ω
ESD Withstand Voltage <sup>1</sup>	V <sub>ESD</sub>	IEC 61000-4-2 (Contact Discharge)	±30			kV
		IEC 61000-4-2 (Air Discharge)	±30			kV
Diode Capacitance <sup>1</sup>	C <sub>I/O-GND</sub>	Reverse Bias=0V, f=1MHz, I/O to GND		1	3	pF
	C <sub>I/O-I/O</sub>	Reverse Bias=0V, f=1MHz, I/O to I/O		0.5		pF

- 1. Parameter is guaranteed by design and/or component characterization.
  2. Transmission Line Pulse (TLP) test setting: Std.TDR(50Ω),tp=100ns, tr=0.2ns ITLP and VTLP averaging window: start t1=70ns to end t2=80ns

#### 8/20µs Pulse Waveform

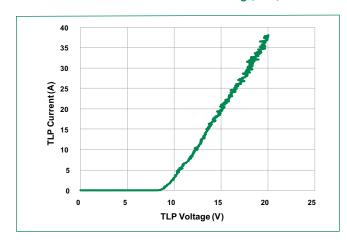


#### Capacitance vs. Reverse Bias

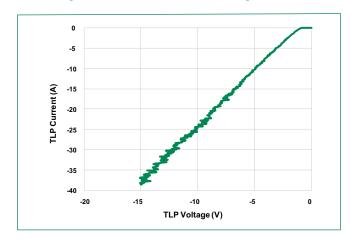




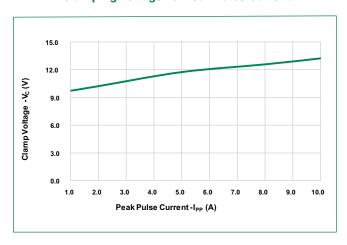
#### Positive Transmission Line Pulsing (TLP) Plot



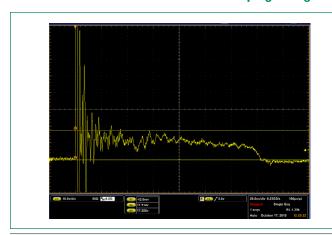
#### **Negative Transmission Line Pulsing (TLP) Plot**



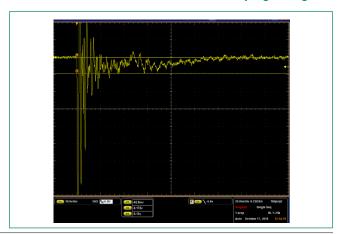
#### **Clamping Voltage vs. Peak Pulse Current**



#### IEC 61000-4-2 +8 kV Contact ESD Clamping Voltage



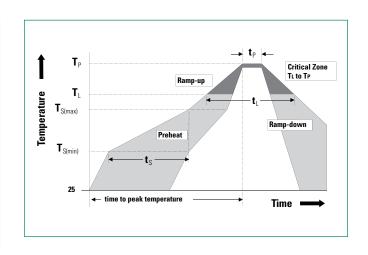
#### IEC 61000-4-2 -8 kV Contact ESD Clamping Voltage





### **Soldering Parameters**

Reflow Condition		Pb – Free assembly	
Pre Heat	-Temperature Min (T <sub>s(min)</sub> )	150°C	
	-Temperature Max (T <sub>s(max)</sub> )	200°C	
	-Time (min to max) (t <sub>s</sub> )	60 - 120 secs	
Average ramp up rate (Liquidus) Temp $(T_L)$ to peak		3°C/second max	
T <sub>S(max)</sub> to T <sub>L</sub> - Ramp-up Rate		3°C/second max	
Reflow	-Temperature (T <sub>L</sub> ) (Liquidus)	217°C	
	-Temperature (t <sub>L</sub> )	60 - 150 seconds	
Peak Temperature (T <sub>p</sub> )		260+0/-5 °C	
Time within	n 5°C of actual peak Temperature (t <sub>p</sub> )	30 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T <sub>p</sub> )		8 minutes Max.	
Do not exceed		260°C	



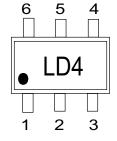
#### **Ordering Information**

Part Number	Package	Min. Order Qty.
SRV05-4HTG-D	SOT23-6	3000

#### **Product Characteristics**

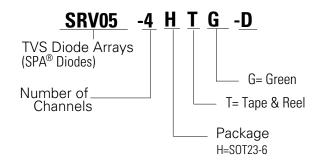
Lead Plating	Matte Tin
Lead Material	Copper Alloy
Lead Coplanarity	0.004 inches(0.102mm)
Substrate Material	Silicon
Body Material	Molded Compound
Flammability	UL Recognized compound meeting flammability rating V-0

#### **Part Marking System**



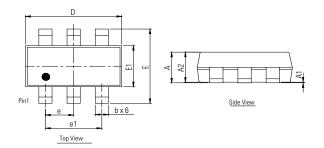
L : Part code D : Assembly code 4 : Number of channel

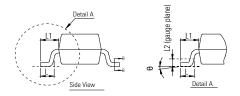
#### **Part Numbering System**

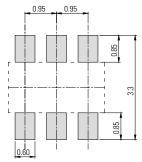




#### Package Dimensions - SOT23-6





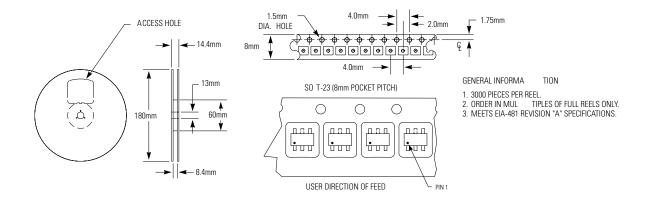


Recommended soldering pad layout (unit :mm)

Symbol	Millimeters			Inches			
	Min	Nom	Max	Min	Nom	Max	
Α	-	-	1.45	-	-	0.057	
<b>A</b> 1	0.00	-	0.15	0.000	-	0.006	
A2	0.90	1.15	1.30	0.035	0.045	0.051	
b	0.30	-	0.50	0.012	-	0.020	
D	2.70	2.90	3.05	0.106	0.114	0.120	
E	2.60	2.80	3.00	0.102	0.110	0.118	
E1	1.45	1.60	1.75	0.057	0.063	0.069	
е	0.95 BSC			0.037 BSC			
e1	1.90 BSC			0.075 BSC			
L	0.30	0.50	0.60	0.012	0.020	0.024	
L1	0.60 REF			0.024 REF			
L2	0.25 BSC			0.010 BSC			
Θ	0°	4°	8°	0° 4° 8°			

#### Embossed Carrier Tape & Reel Specification — SOT23-6

8mm TAPE AND REEL



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